

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1587CM-3.6#PBF		(Engineering Calculation)		DDPAK				
(printed on: 7/26/2011 5:59:56 AM)				TOTAL MASS (g):		1.375959		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004895	1000000	3557.52		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.827657	998500	601512.9		
		Iron (Fe)	7439-89-6	0	0	0		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0.001243	1500	903.3702		
		Lead Frame Total:				0.830143	1000000	603319.7
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.009684741	1000000	7038.54		
		External Plating Total:				0.009684741	1000000	7038.54
		Inter. Plating Ni	7440-02-0	0.005	781250	3633.83		
		Inter. Plating Ag	7440-22-4	0.0014	218750	1017.472		
		Internal Plating Total:				0.0064	1000000	4651.302
Die Attach	95Pb / 5 Sn	Silver (Ag)	7440-22-4	0	0	0		
		Tin (Sn)	7440-31-5	0.000112	50000	81.3978		
		Lead (Pb)	7439-92-1	0.002131	950000	1548.738		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0	0	0		
Die Attach Total:				0.002243	1000000	1630.136		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.053704	103000	39030.24		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.466653	895000	339147.5		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.001043	2000	758.017		
Encapsulation Total:				0.5214	1000000	378935.8		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001193	1000000	867.0319		
Estimated								
TOTAL MASS (g):						1.375959		